

In the Claims

Please amend claims 1, 9 and 12 as follows.

1. (Twice Amended) A leadframe for a semiconductor device, the leadframe comprising:

a paddle ring having an inner perimeter, an outer perimeter, and a cavity located within the inner perimeter for receiving an integrated circuit die, the paddle ring outer perimeter including outwardly extending leads that terminate in a first row of terminals generally surrounding the paddle ring outer perimeter; and

a second row of terminals surrounding the first row of terminals, wherein each of the terminals of the second row of terminals is connected to a connection bar and wherein the first row of terminals is connected to the second row of terminals at a corner of the connection bar.

9. (Twice Amended) The leadframe of claim 8, further comprising another row of terminals connected to a first side of the connection bar opposing a second side of the connection bar to which the second row of terminals is connected, said another row of terminals for connecting to a second integrated circuit die.

12. (Twice Amended) A semiconductor device, comprising:

a paddle ring having an inner perimeter, an outer perimeter, and a cavity located within the inner perimeter, the paddle ring outer perimeter including outwardly extending leads that terminate in a first row of terminals generally surrounding the paddle ring outer perimeter;

a second row of terminals surrounding the first row of terminals, wherein each of the terminals of the second row of terminals is connected to a connection bar and wherein the first row of terminals is connected to the second row of terminals at a corner of the connection bar; and

an integrated circuit die placed within the cavity and surrounded by the paddle ring, the die including a plurality of die pads that are electrically connected to respective ones of the terminals of the first and second rows of terminals.